Laser Processing: Via Drill and Ablation

Overview

The Technology Hub at NextFlex offers laser processing to create vias in substrates, ablation to create fine features for direct die attach, serialization and singulation.

Via Drill

SUBSTRATE REQUIREMENTS	
WIDTH ≤ 600 mm	50µm to 500µm Via Diameter
LENGTH ≤ 600 mm	PET and PI substrates
THICKNESS 25µm - 250µm	

Ablation

MINIMUM FEATURE SIZE	MATERIALS
TRACE WIDTH ≥ 40µm	Silver
PITCH ≥ 60µm	Copper

Serialization

- Static Characters
- Dynamic Date
- Increment by substrate
- Increment each device or circuit on substrate
- QR Code and Data Matrix Options

Singulation

For more information, contact NextFlex at info@nextflex.us.

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